Abstract

Apparatus for Manufacturing Semiconductor Devices

The present invention relates to an apparatus for the manufacture of semiconductor devices; comprising a bonding module (1) comprising a vacuum chamber to provide bonding of wafers under pressure below atmospheric pressure; and a load lock module (2) connected to the bonding module (1) and configured for wafer transfer to the bonding module (1) and connected to a first vacuum pumping device (5) configured to reduce the pressure in the load lock module (2) below atmospheric pressure.

Fig. 1